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FIG. 1A

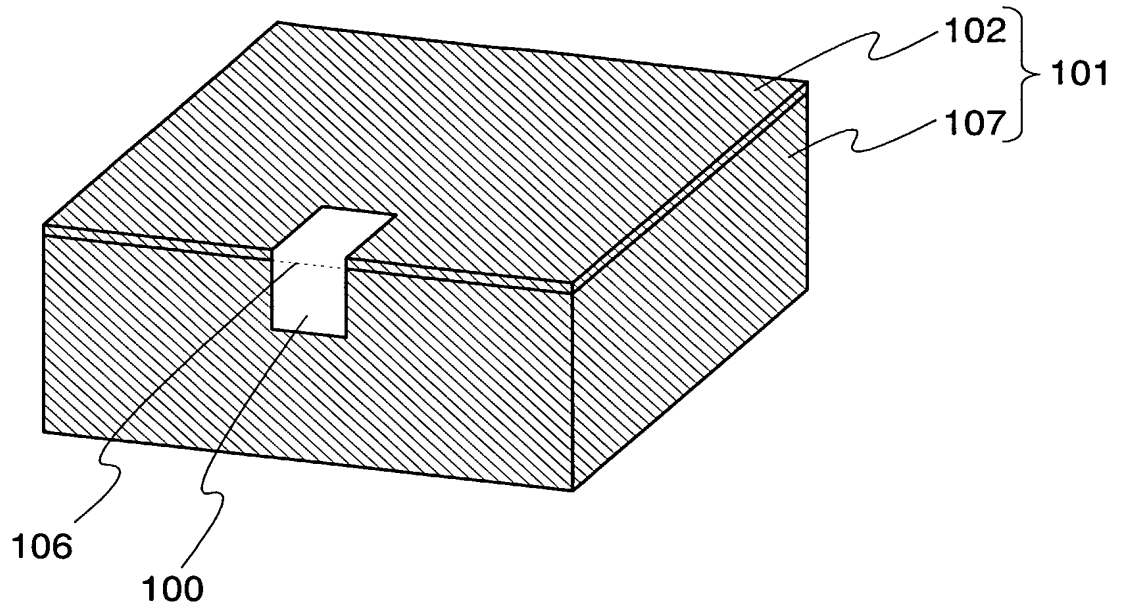
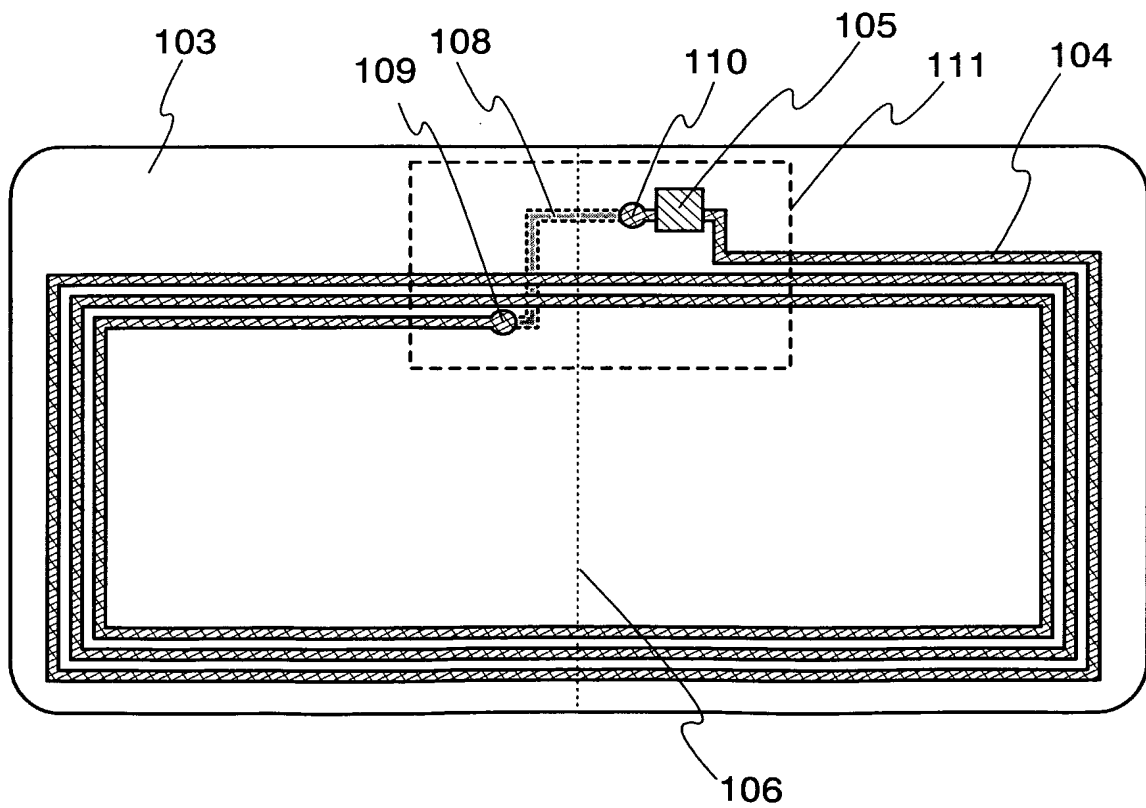


FIG. 1B



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FIG. 2A

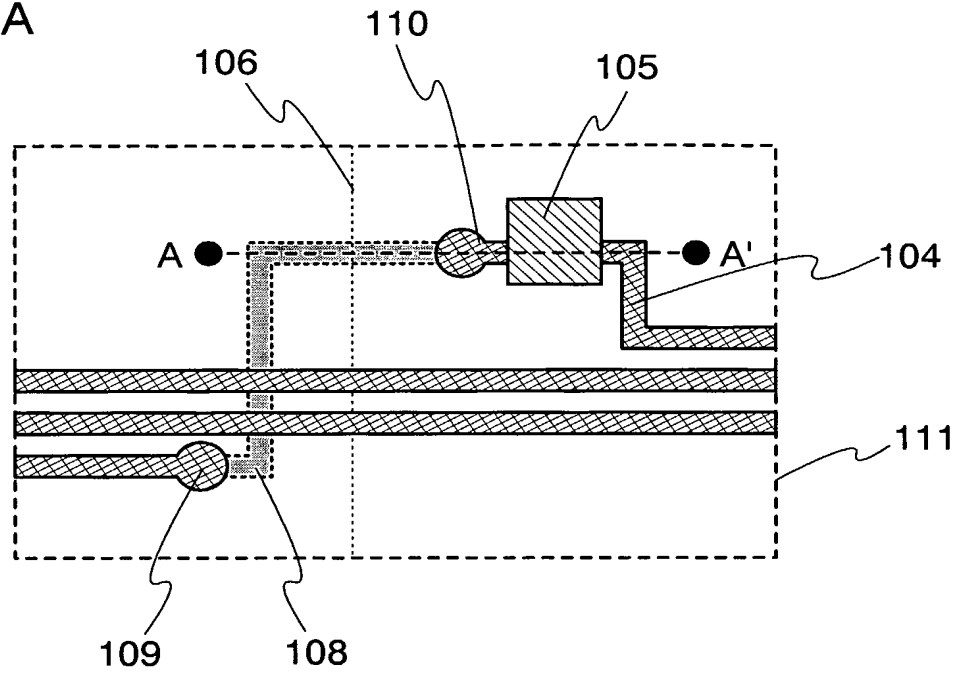


FIG. 2B

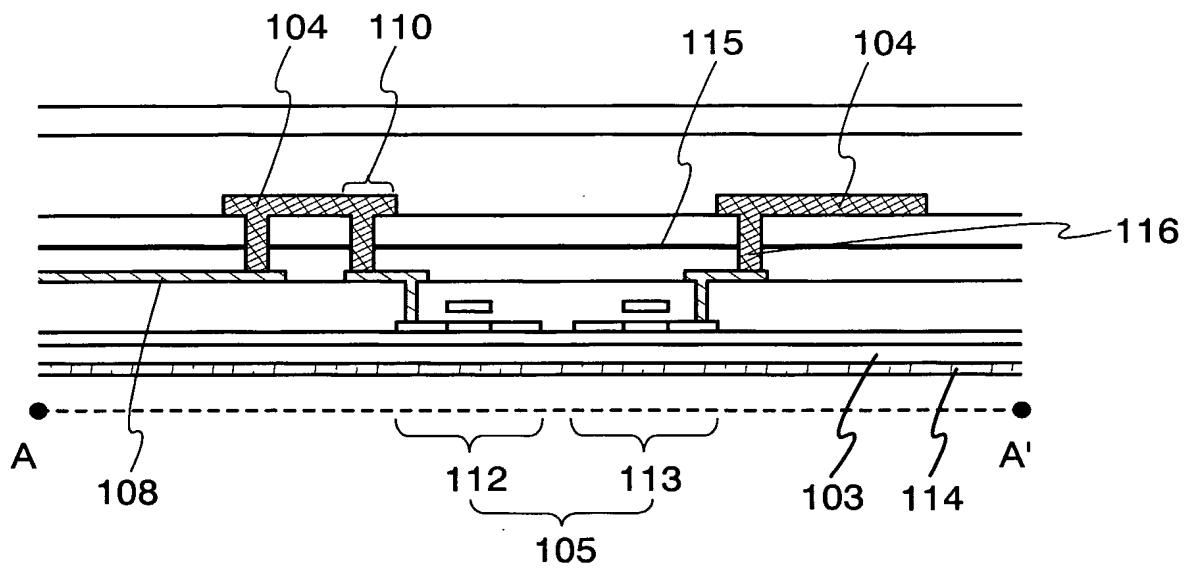


FIG. 3A

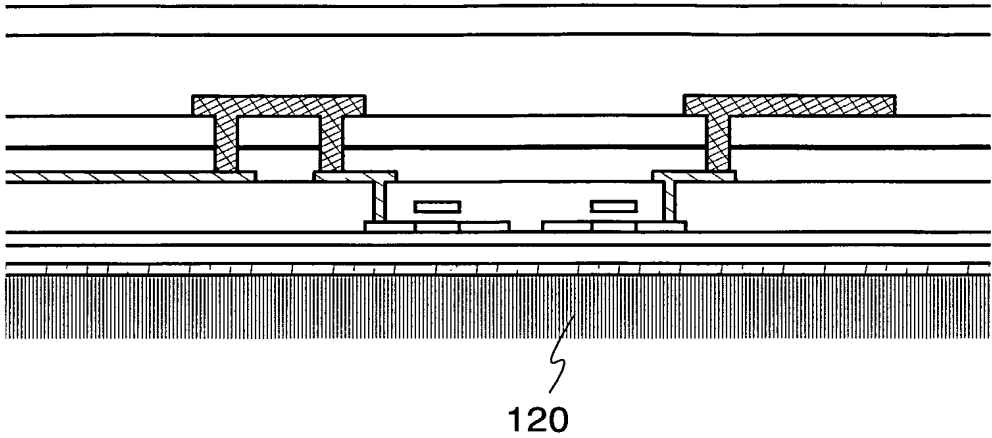
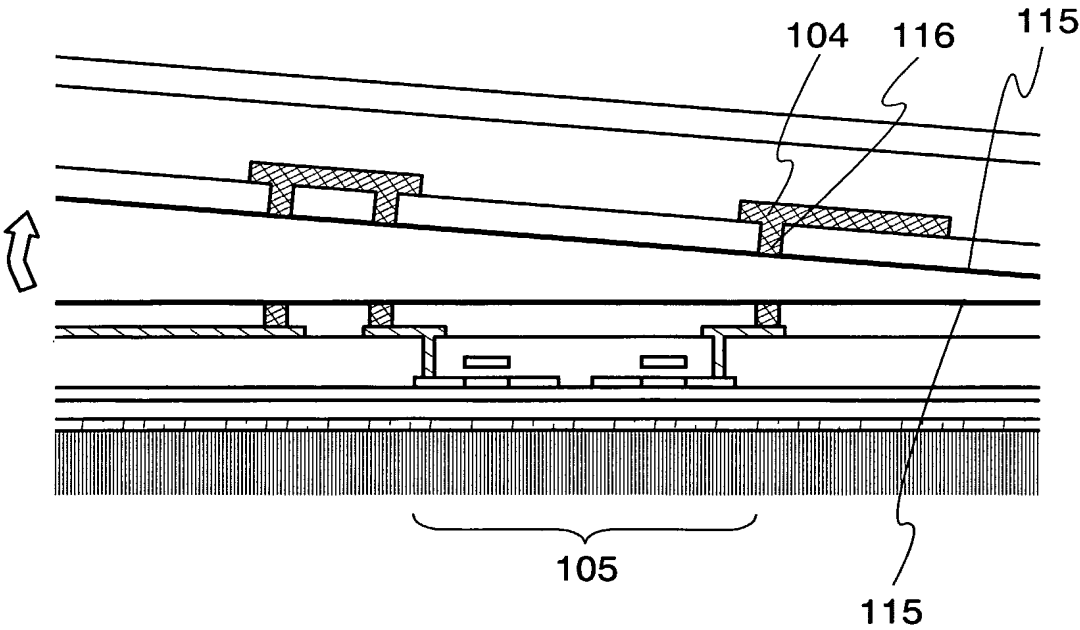


FIG. 3B



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FIG. 4A

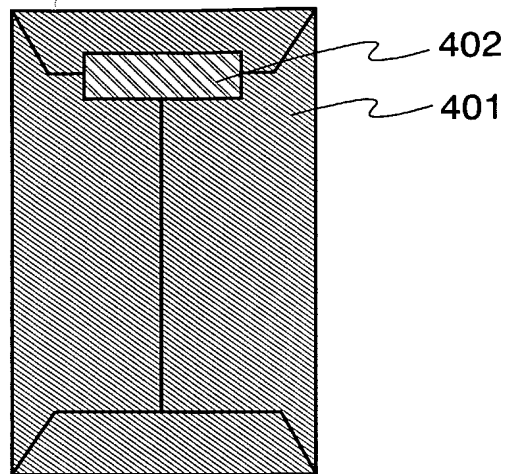
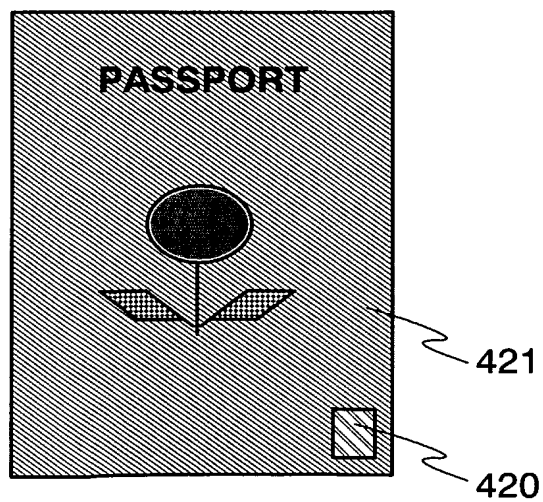


FIG. 4B

FIG. 4B is a check form. The word "CHECK" is printed at the top center. Below it, the following fields are listed: "PLACE OF PAYMENT", "BANK NAME", "BRANCH OFFICE", "AMOUNT", "DATE", "COMPANY", "DRAWER", and "NAME". The "AMOUNT" field contains the value "¥1,234,567✕". To the right of the "AMOUNT" field is a box for a stamp. Below the "COMPANY" field is a box for a seal, labeled "SEAL". The seal box is divided into two sections: a top section with diagonal hatching (411) and a bottom section (410). Reference numerals 411 and 410 point to these sections respectively.

FIG. 4C



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FIG. 5A

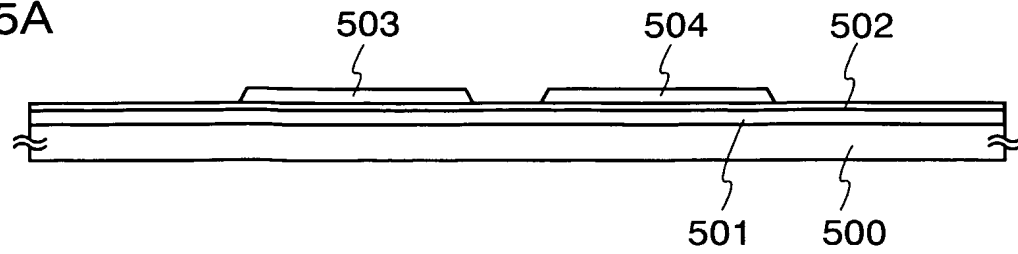


FIG. 5B

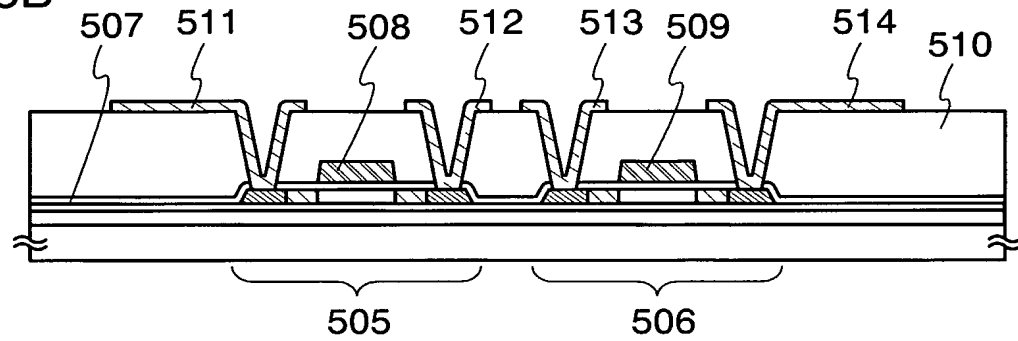


FIG. 5C

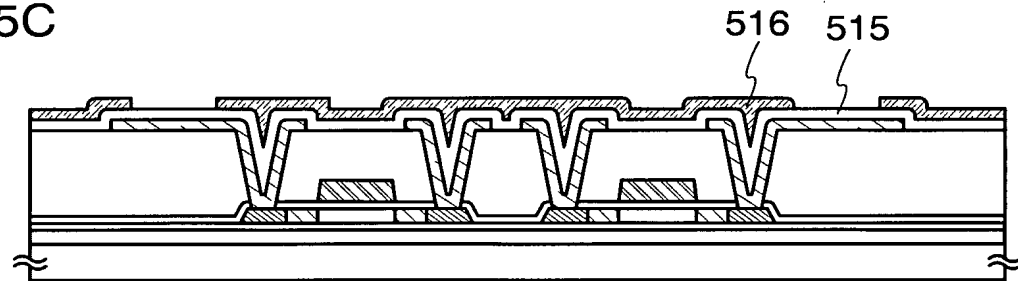


FIG. 5D

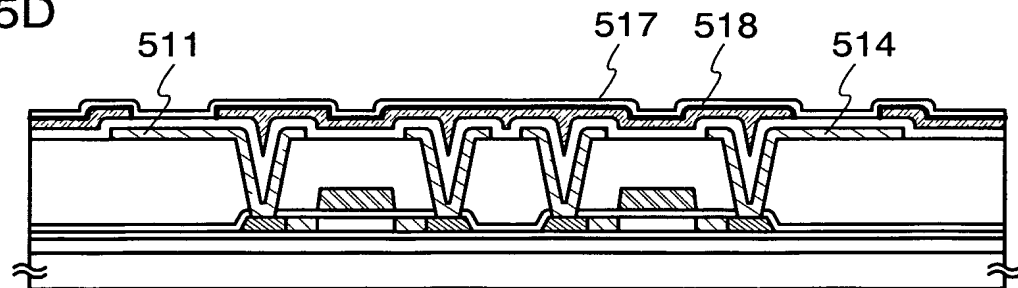
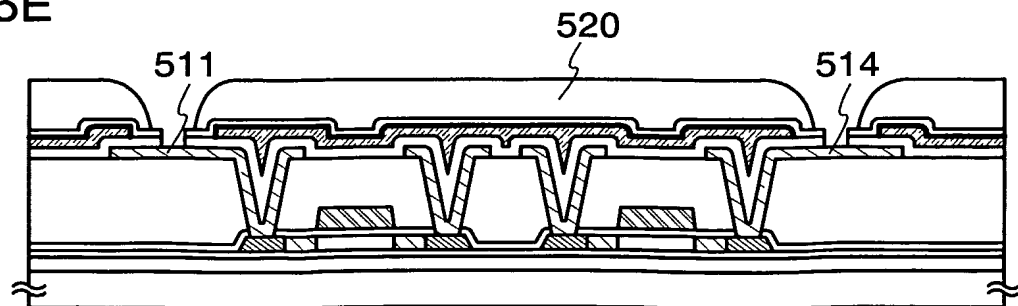


FIG. 5E



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FIG. 6A

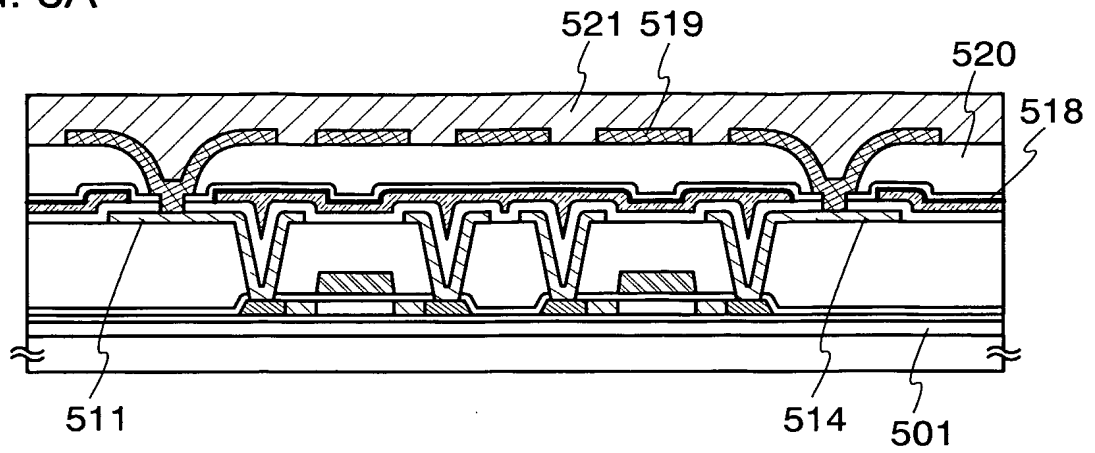


FIG. 6B

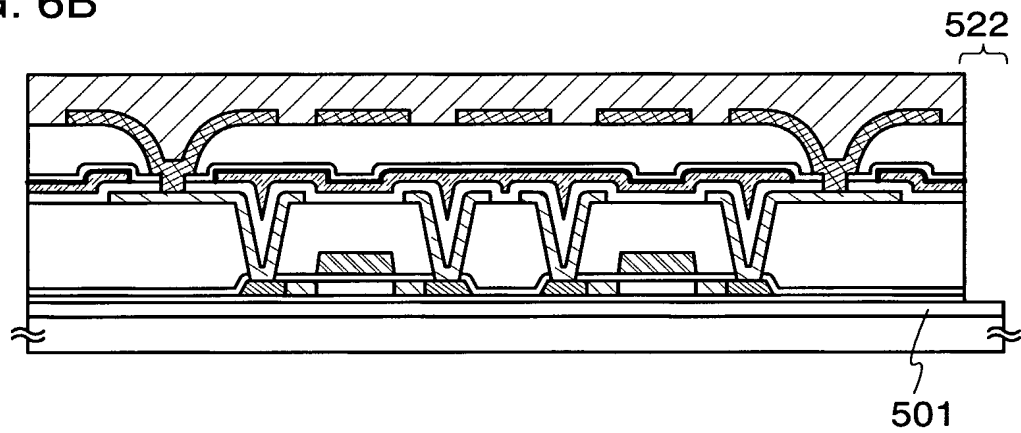
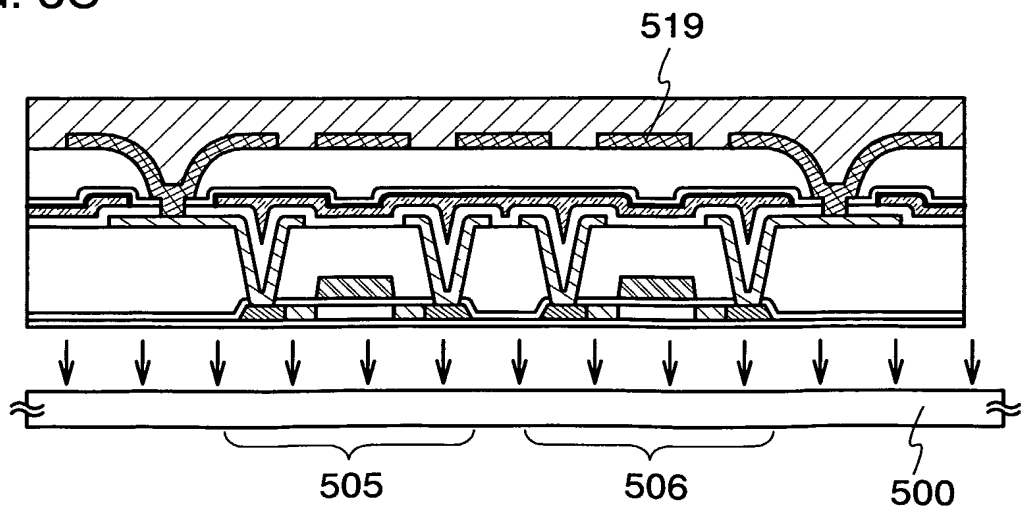


FIG. 6C



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FIG. 7

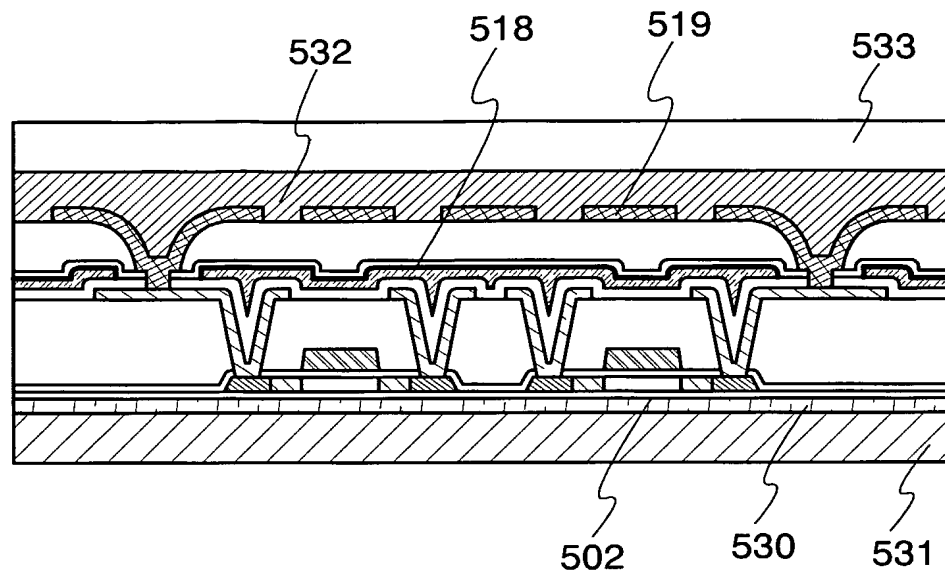


FIG. 8A

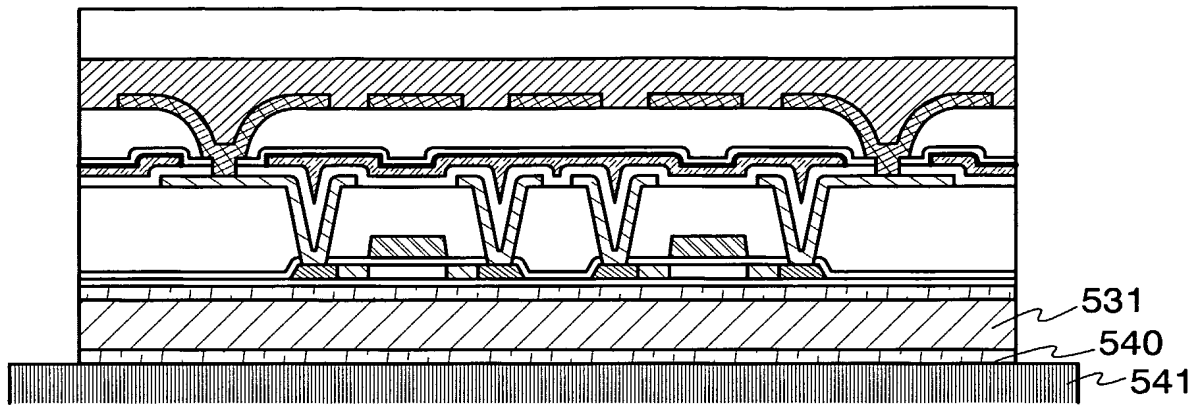
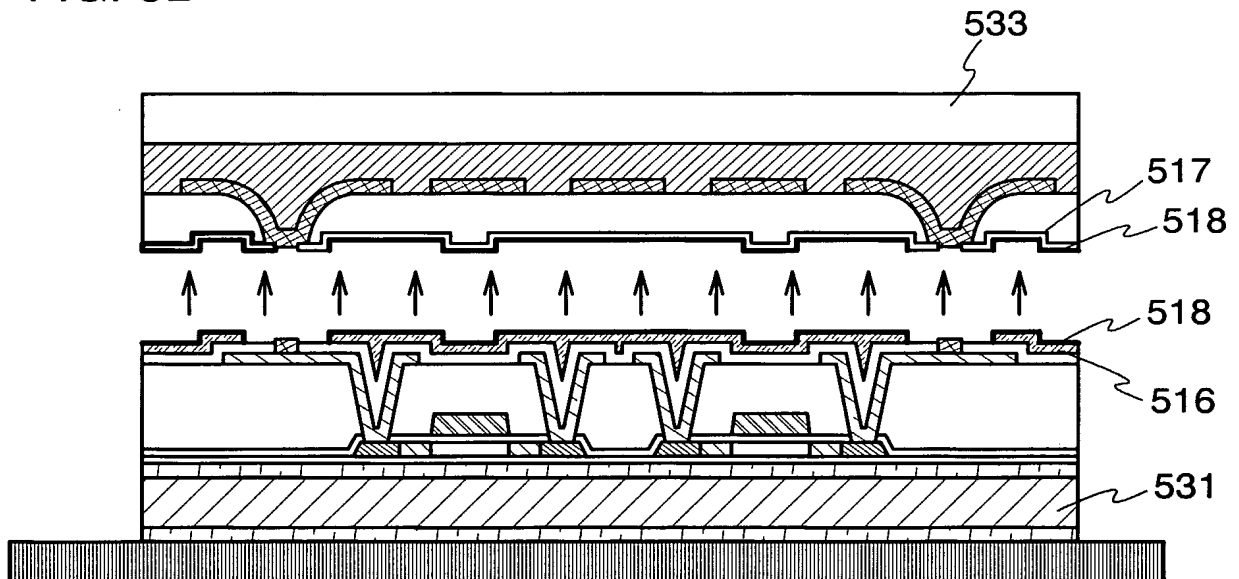


FIG. 8B



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FIG. 9A

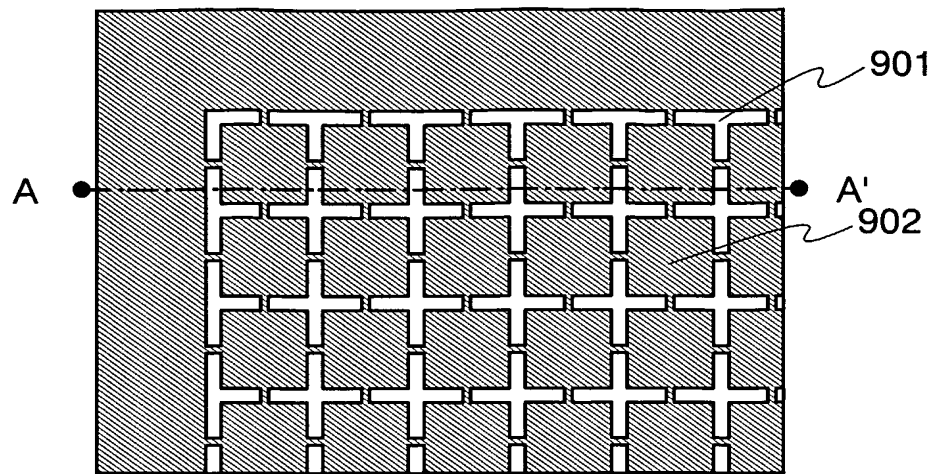


FIG. 9B

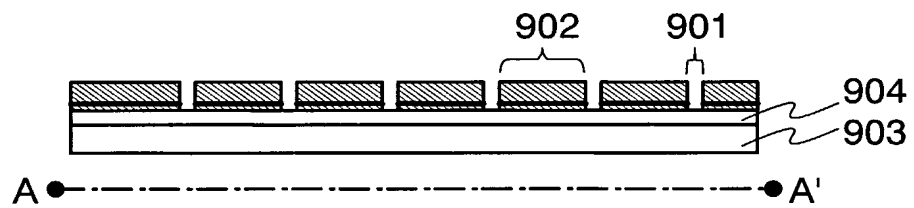


FIG. 9C

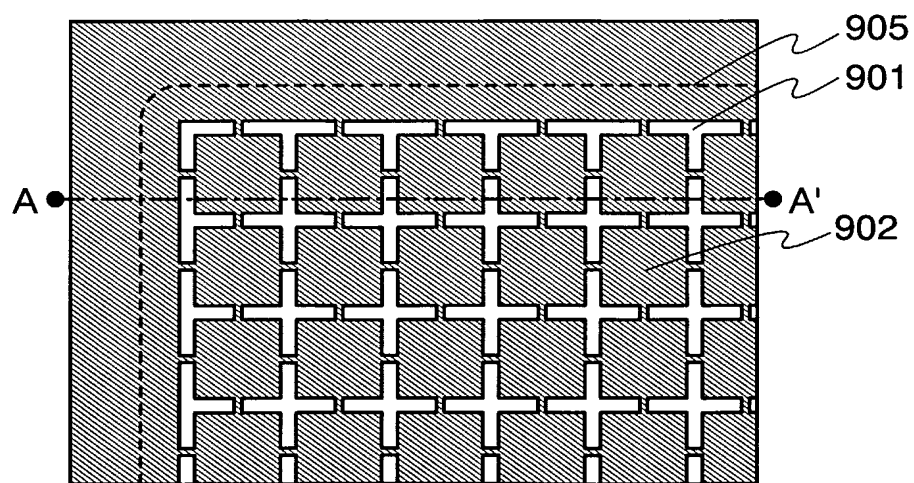
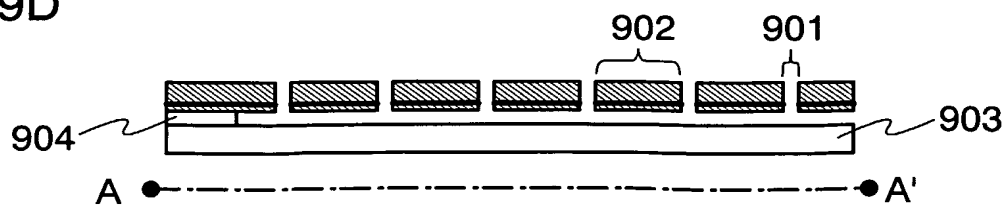
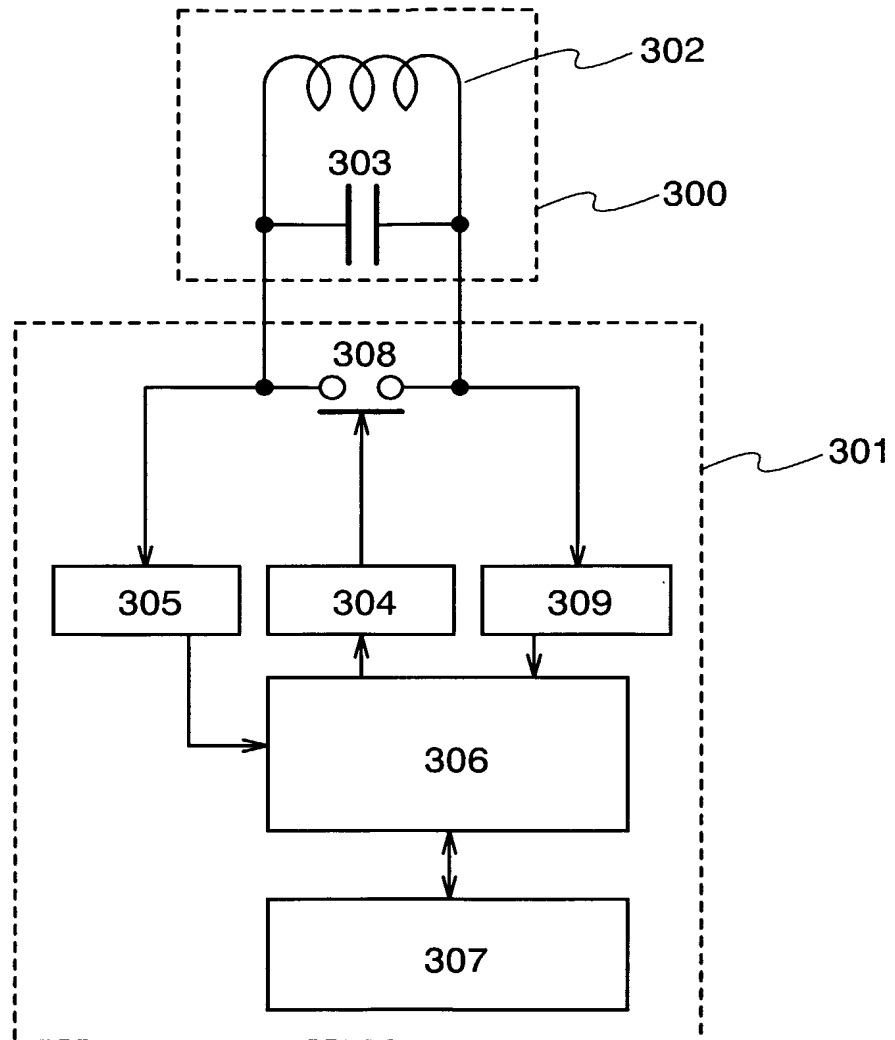


FIG. 9D



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FIG. 10



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FIG. 11A

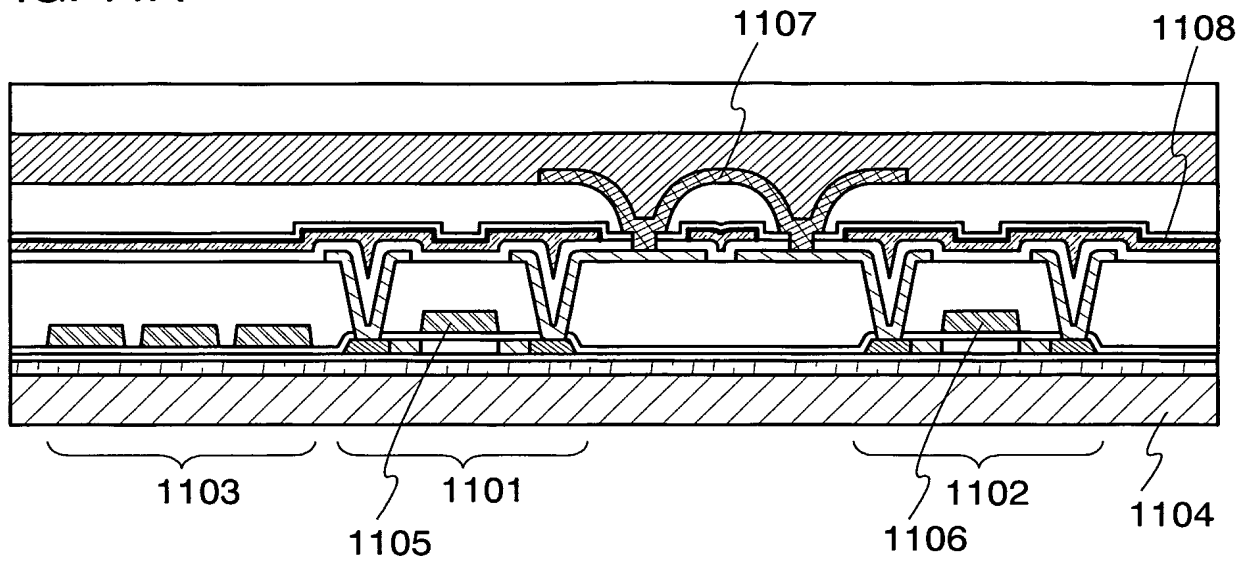
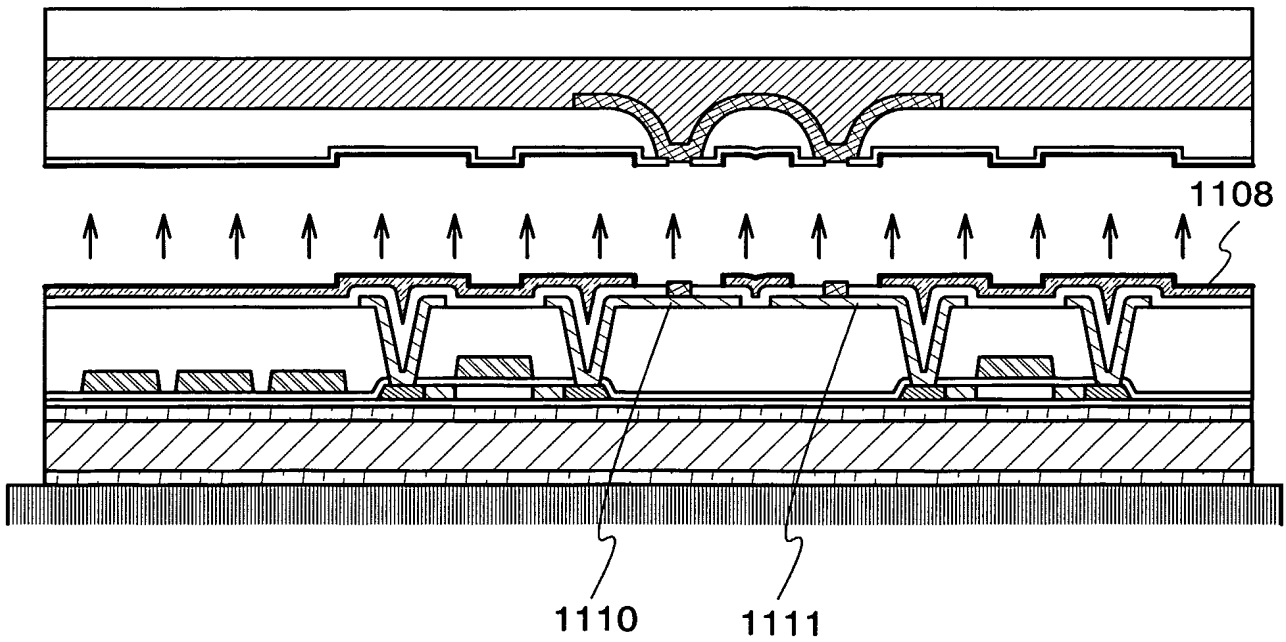


FIG. 11B



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FIG. 12A

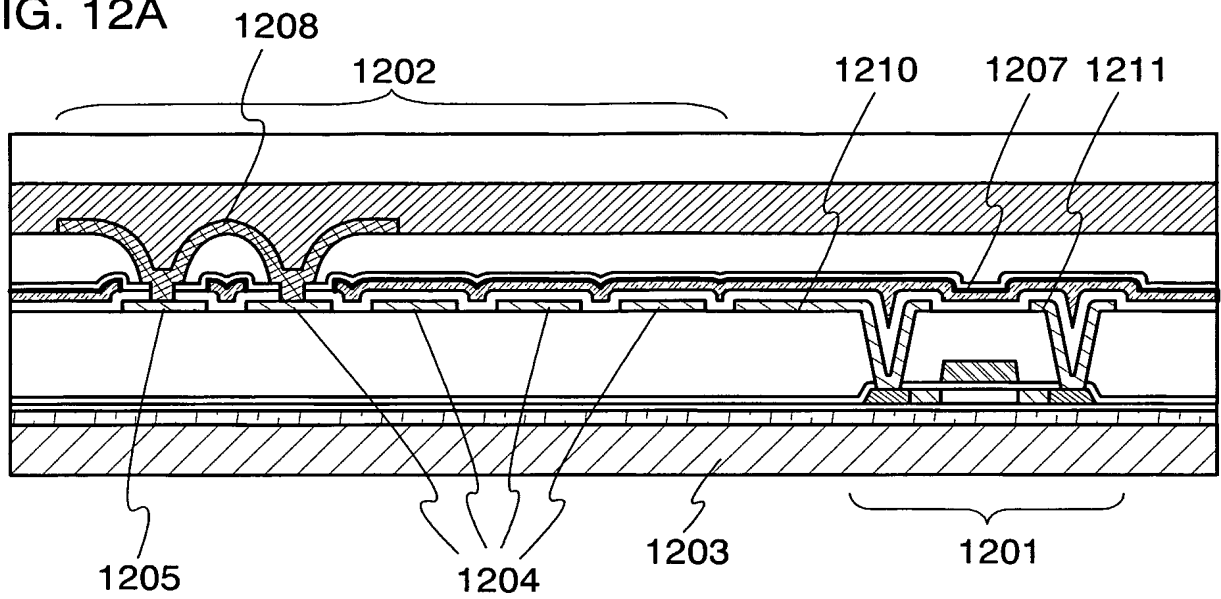
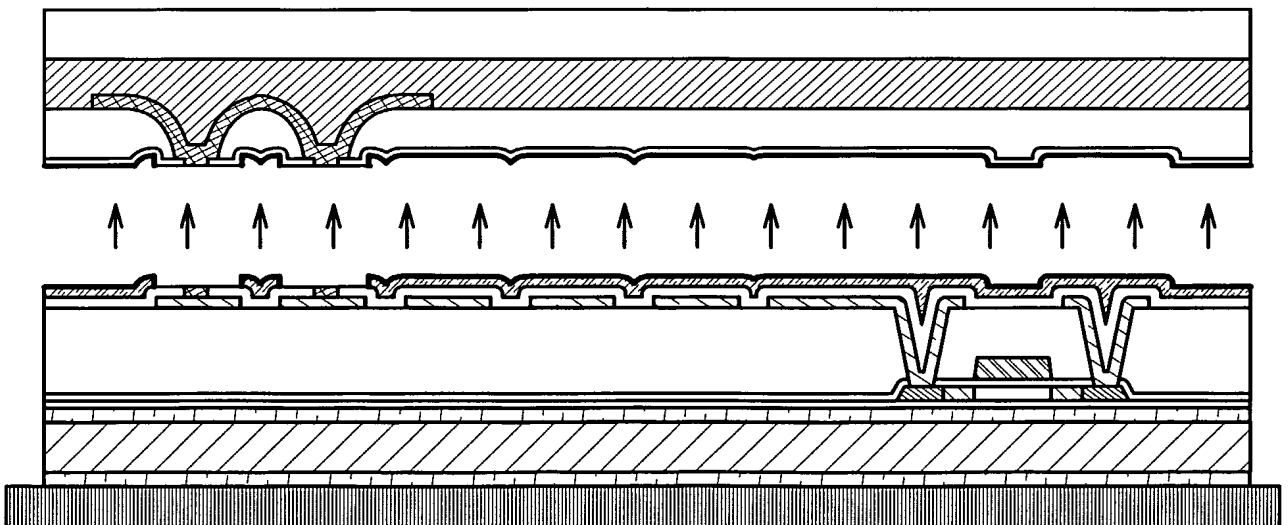


FIG. 12B



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[EXPLANATION OF SYMBOLS]

100: ID tag, 101: container, 102: lid, 103: support base, 104: antenna, 105: thin film integrated circuit, 106: broken line, 107: main body, 108: wiring, 109: terminal, 110: terminal, 111: broken line, 112: TFT, 113: TFT, 114: adhesive, 115: separating layer, 116: wiring, 120: object, 300: antenna, 301: thin film integrated circuit, 302: antenna coil, 303: capacitor, 304: modulating circuit, 305: rectifying circuit, 306: micro processor, 307: memory, 308: switch, 309: demodulating circuit, 401: envelope, 402: ID tag, 410: ID tag, 411: check, 420: ID tag, 421: passport, 500: substrate, 501: peeling layer, 502: base film, 503: semiconductor film, 504: semiconductor film, 505: TFT, 506: TFT, 507: gate insulating film, 508: gate electrode, 509: gate electrode, 510: first interlayer insulating film, 511: wiring, 512: wiring, 513: wiring, 514: wiring, 515: second interlayer insulating film, 516: metal film, 517: oxide film, 518: metal oxide film, 519: antenna, 520: third interlayer insulating film, 521: protective layer, 522: groove, 530: adhesive, 531: support base, 532: adhesive, 533: cover material, 540: adhesive, 541: object, 901: groove, 902: thin film integrated circuit, 903: substrate, 904: peeling layer, 905: broken line, 1101: TFT, 1102: TFT, 1103: antenna, 1104: support base, 1105: gate electrode, 1106: gate electrode, 1107: wiring, 1108: metal oxide film, 1110: wiring, 1111: wiring, 1201: TFT, 1202: antenna, 1203: support base, 1204: wiring, 1205: wiring, 1207: metal oxide film, 1208: wiring, 1210: wiring, 1211: wiring